DATA	SHEET	
PART NO.:	L-C192WDT	
DEX		
KEV	7: <u>C/0</u>	
CUSTOMER'S APPROVAL :	D0	CC :
DRAWING NO. : DS-75-05-0005	DATE : 2021-11-20	Page 1 LD-R/R005

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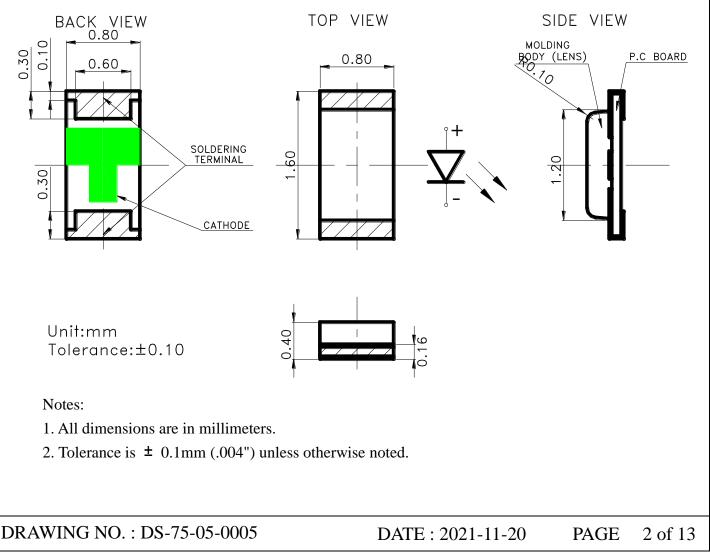
## Part No. : L-C192WDT

**REV:** C/0

### • Features

- \* Extra thin 0.4mm, Top view, Wide view angle, White color SMD chip LED.
- \* Special for Cellular Phone keypad / LCD backlighting or thin touch button LED backlighting.
- \* Packing in 8mm tape on 7" diameter reels.
- \* Compatible with automatic Pick & Place equipment.
- \* Compatible with Reflow soldering and Wave soldering processes.
- \* EIA STD package.(ANSI/EIA-481-B-2001)
- \* I.C. compatible, low current application
- \* Pb free product and acceptable lead-free process!.
- \* Meet RoHS Green Product.
- \* Moisture sensitivity level: 3

## • PACKAGE OUTLINE DIMENSIONS



## Part No. : L-C192WDT

#### REV: C/0

### • CHIP MATERIALS

- \* Dice Material : InGaN
- \* Light Color : White
- \* Lens Color : Light Yellow Diffused.

### • Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit	
PD	Power Dissipation	75	mW	
IPF	Peak Forward Current	80		
IPF	(1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA	
IF	Continuous Forward Current	20	mA	
VR	Reverse Voltage	5	V	
ESD	Electrostatic Discharge Threshold(HBM)Note A	1000	V	
Topr	Operating Temperature Range	-40 ~ + 85	°C	
Tstg	Storage Temperature Range	-40 ~ + 85	°C	

#### Note A :

HBM : Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

### • Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition	
Luminous Intensity	IV	71	150	280	mcd	IF=5mA	
Viewing Angle	2 <sup>θ</sup> 1/2		130		Deg	Note 2	
CIE Chromaticity	X		0.30			IF=5mA	
CIE Chromaticity	Y		0.30				
Forward Voltage	VF	2.7	2.8	3.2	V	IF = 5mA	
Reverse Current	IR			50	μA	VR = 5V	

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## Part No. : L-C192WDT

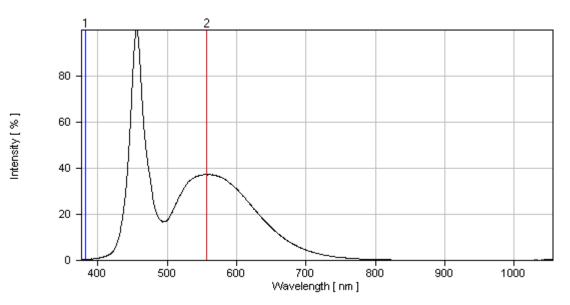
#### Notes:

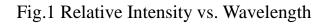
- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2.  $\theta$  1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

4. Major standard testing equipment by "Instrument System" Model : CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model : 2400.

### • Typical Electro-Optical Characteristics Curves





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## Part No. : L-C192WDT

### • Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

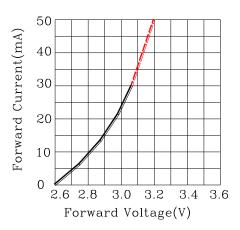


Fig.1 Forward Current vs.Forward Voltage

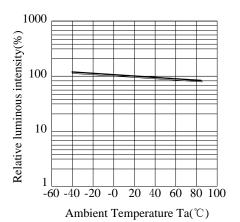
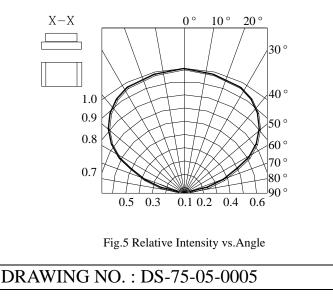


Fig.3Luminous Intensity vs.Ambient Temperature



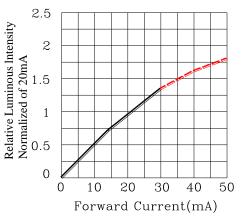


Fig.1 Relative Luminous Intensity vs.Forward Current

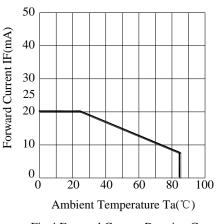


Fig.4 Forward Current Derating Curve

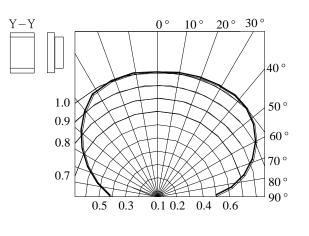
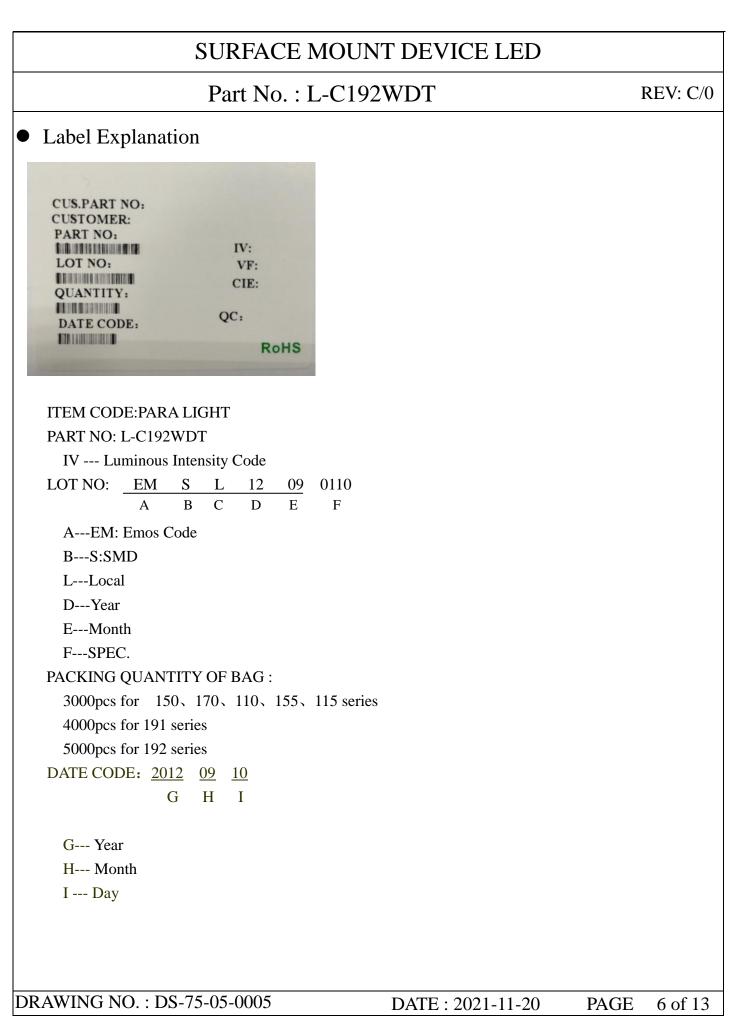


Fig.6 Relative Intensity vs.Angle

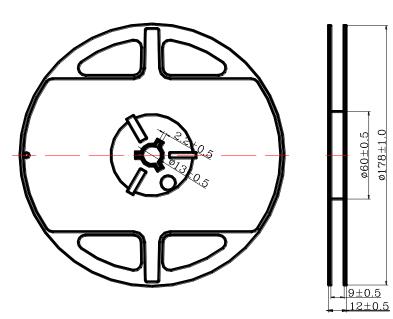
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REV: C/0

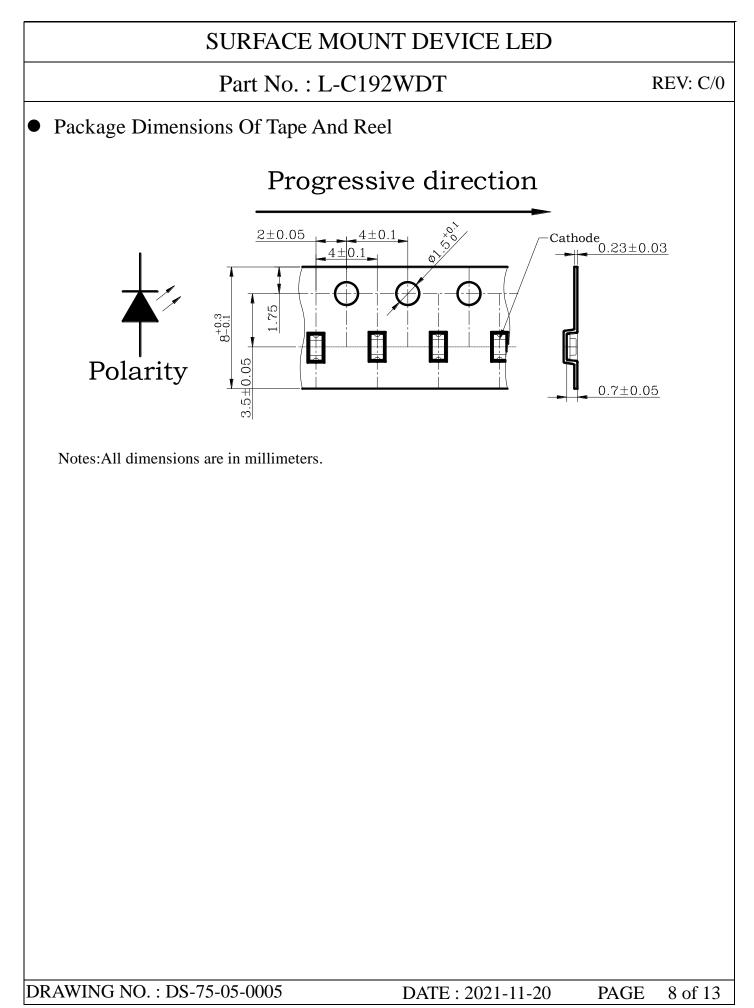
• Reel Dimensions



Notes:

- 1. Taping Quantity : 3000pcs, (Minimum packing quantity will be 500 pcs for remainders)
- 2. The tolerances unless mentioned is  $\pm 0.1$  mm, Angle  $\pm 0.5^{\circ}$ , Unit : mm.

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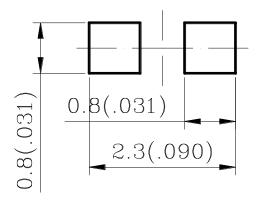
## Part No. : L-C192WDT

REV: C/0

### Cleaning

- \* If cleaning is required, use the following solutions for less than 1 minute and less than  $40^{\circ}$ C.
- \* Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

### • Suggest Soldering Pad Dimensions



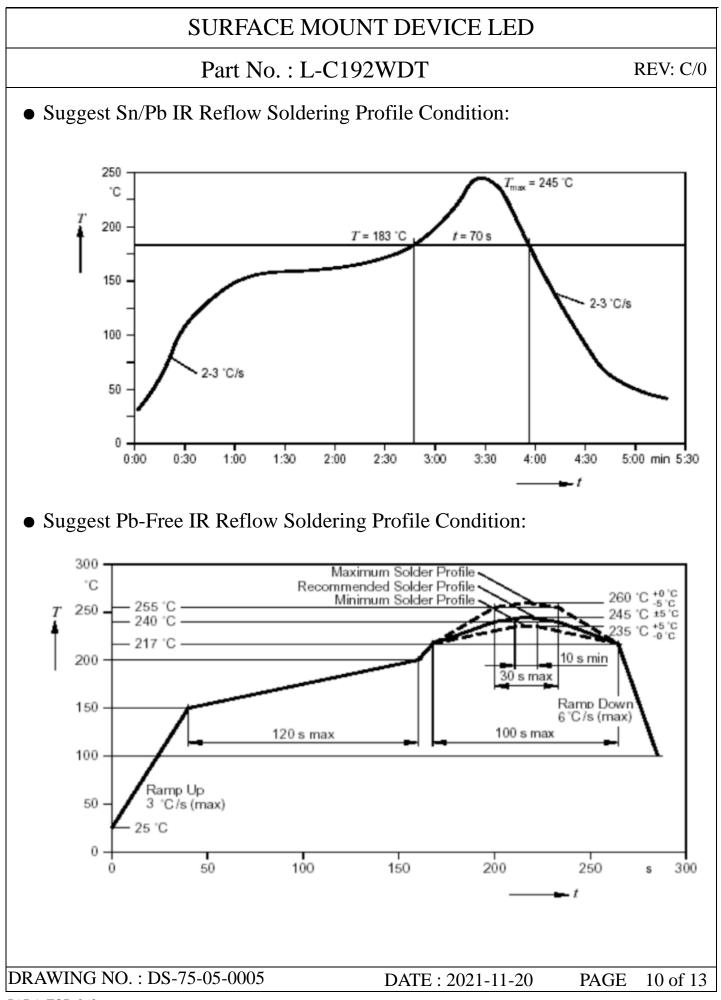
Direction of PWB camber

and go to reflow furnace

Notes : Suggest stencil print screen thickness are 0.10mm maximum.

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## Part No. : L-C192WDT

#### REV: C/0

### • Bin Code List

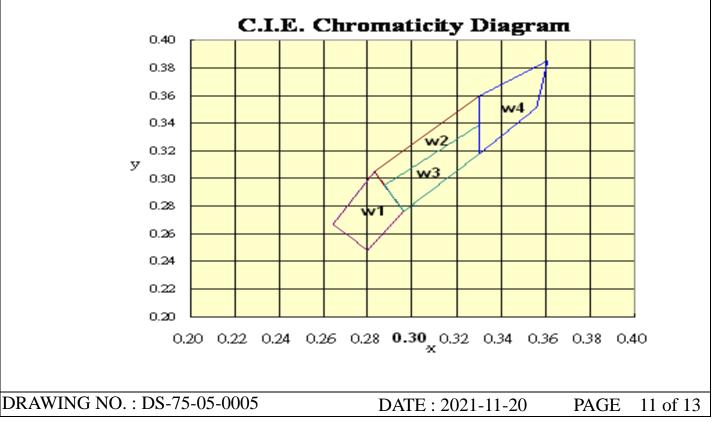
Luminous Intensity(IV), Unit:mcd@5mA			_	Forward Voltage(VF), Unit:V@5m			
Bin Code	Min	Max		Bin Code	Min	Max	
Q	71	112		12	2.7	2.8	
R	112	180		13	2.8	2.9	
S	180	280		14	2.9	3.0	
				15	3.0	3.1	
				16	3.1	3.2	

Tolerance of each bin are  $\pm 15\%$ 

Tolerance of each bin are  $\pm 0.1$  Volt

Color Rank (CIE chromaticity X, Y) @ 5mA									
Rank W1			Rank W2						
Х	0.280	0.264	0.283	0.296	Х	0.287	0.283	0.330	0.330
Y	0.248	0.267	0.305	0.276	Y	0.295	0.305	0.360	0.339
Rank W3				Rank W4					
Х	0.296	0.287	0.330	0.330	Х	0.330	0.330	0.361	0.356
Y	0.276	0.295	0.339	0.318	Y	0.318	0.360	0.385	0.351

\* Measurement of Color coordinates : +/- 0.02



### Part No. : L-C192WDT

REV: C/0

## • CAUTIONS

1. Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment(such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

#### 2.Storage :

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at  $30^{\circ}$ C or less and 90% RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment:  $60\pm5^{\circ}$ C for 24 hours

#### 3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150 °C, 120sec. MAX., Peak temperature : 240 °C Max. Soldering time : 10 sec Max. Soldering Iron : (Not recommended)

Temperature 300  $^{\circ}$  C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering. Wave soldering :

Pre-heat 100  $^{\circ}$  Max, Pre-heat time 60 sec. Max, Solder wave 260  $^{\circ}$  Max, Soldering time 5 sec. Max. performed consecutively cooling process is required between 1<sup>st</sup> and 2<sup>nd</sup> soldering processes.

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### Part No. : L-C192WDT

REV: C/0

4. Lead-Free Soldering

For Reflow Soldering :

- 1. Pre-Heat Temp: 150-180°C,120sec.Max.
- 2. Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、Peak Temperature: 260°C, 5sec.
- 4. Reflow Repetition: 2 Times Max.
- 5. Suggest Solder Paste Formula : 93.3 Sn/3.1 Ag/3.1 Bi/0.5 Cu

For Soldering Iron (Not Recommended) :

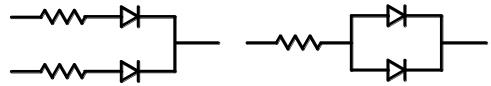
- 1. Iron Tip Temp: 350°C Max.
- 2. Soldering Iron: 30w Max.
- 3. Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering :

- 1. Pre-Heat Temp: 150°C Max. 120 Sec. Max.
- 2、Bath Temp: 265°C Max.
- 3、 Dip Time: 5 Sec. Max.
- 5. Drive Method

Circuit model A

Circuit model B



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.